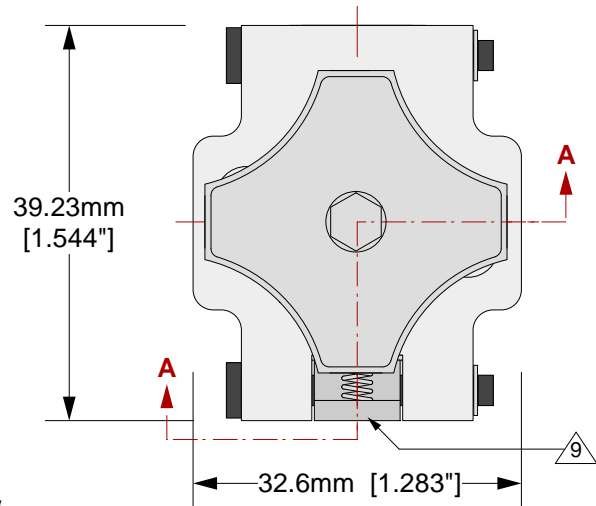
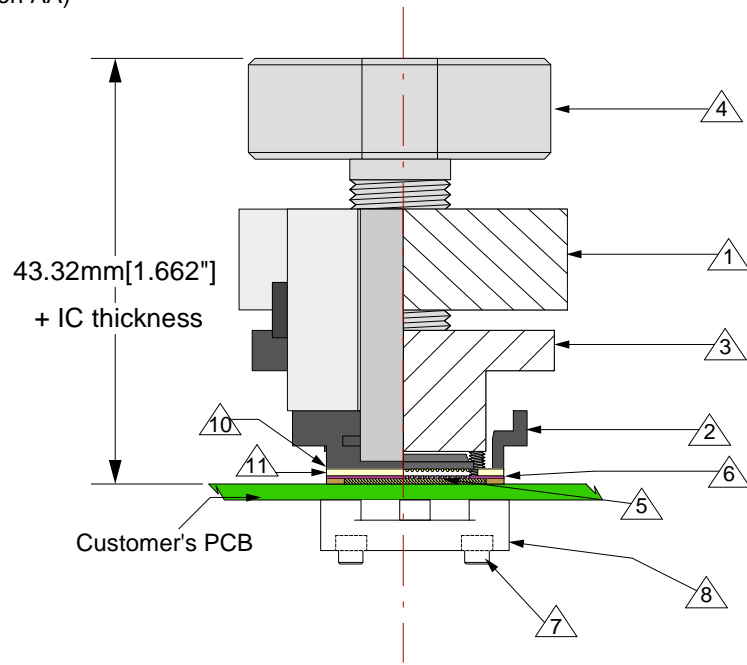


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

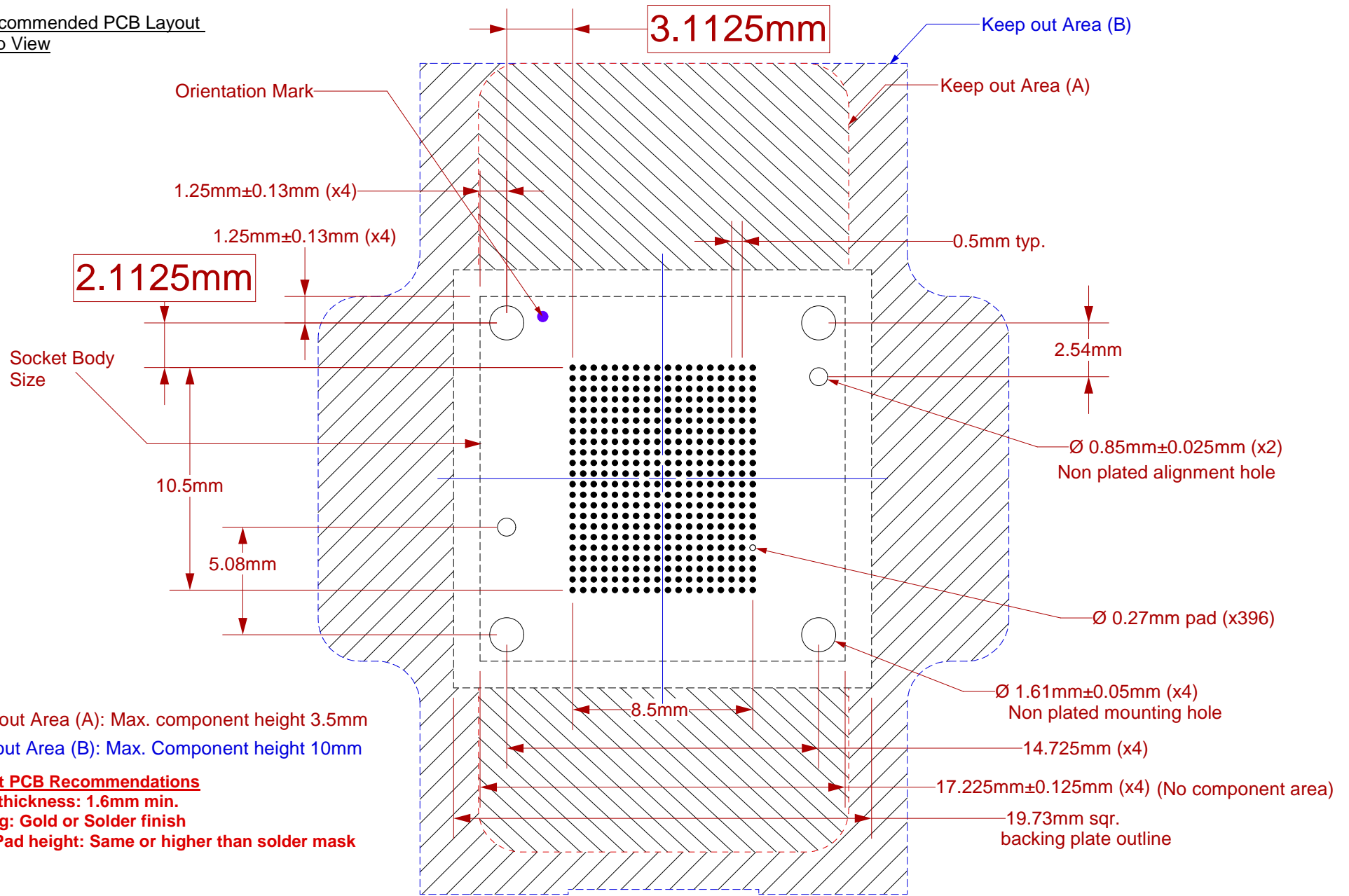
Materials:

- ① Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- ② Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- ③ Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- ④ Fluted Knob Screw: Clear anodized 7075 Aluminum.
- ⑤ Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- ⑥ Elastomer Guide: Ultem 1000. Thickness: 0.425mm
- ⑦ Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8\" long.
- ⑧ Backing Plate: Black anodized 7075 Aluminum
- ⑨ Latch: Black anodized 7075 Aluminum.
- ⑩ IC guide: Ultem
- ⑪ Ball guide: Kapton

	CG-BGA-5005 Drawing		Status: Released	Scale: -	Rev: A
	© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: Vinayak R		Date: 8/31/09
			File: CG-BGA-5005 Dwg	Modified:	

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




Keep out Area (A): Max. component height 3.5mm
Keep out Area (B): Max. Component height 10mm

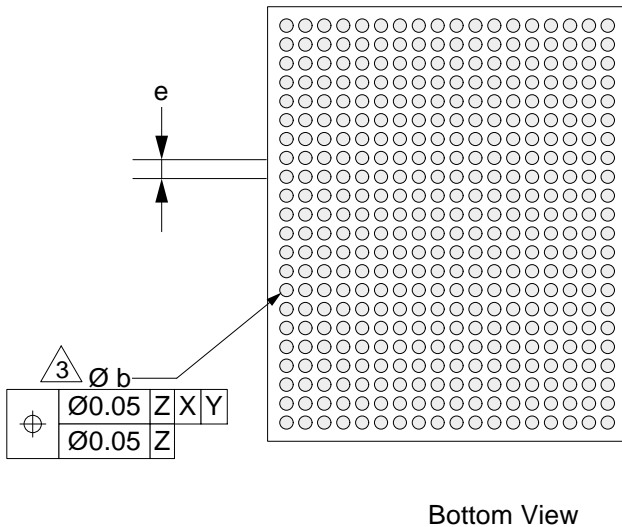
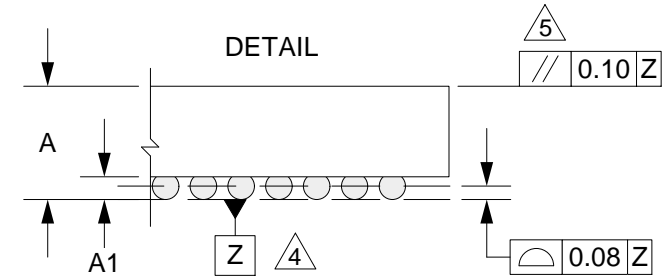
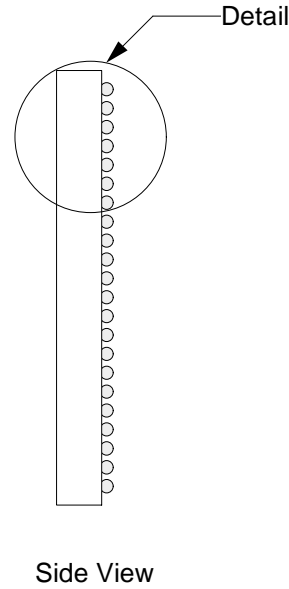
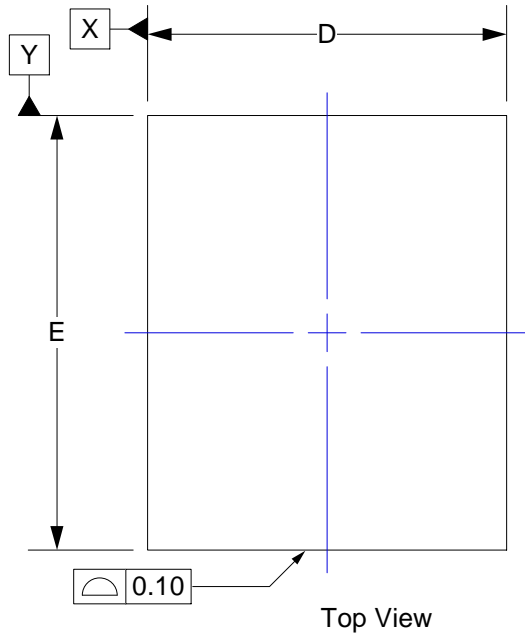
Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

 <p>© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>CG-BGA-5005 Drawing</p>	<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: A</p>
	<p>Drawing: Vinayak R</p>	<p>Date: 8/31/09</p>		<p>Modified:</p>
	<p>File: CG-BGA-5005 Dwg</p>			


Compatible BGA Spec.



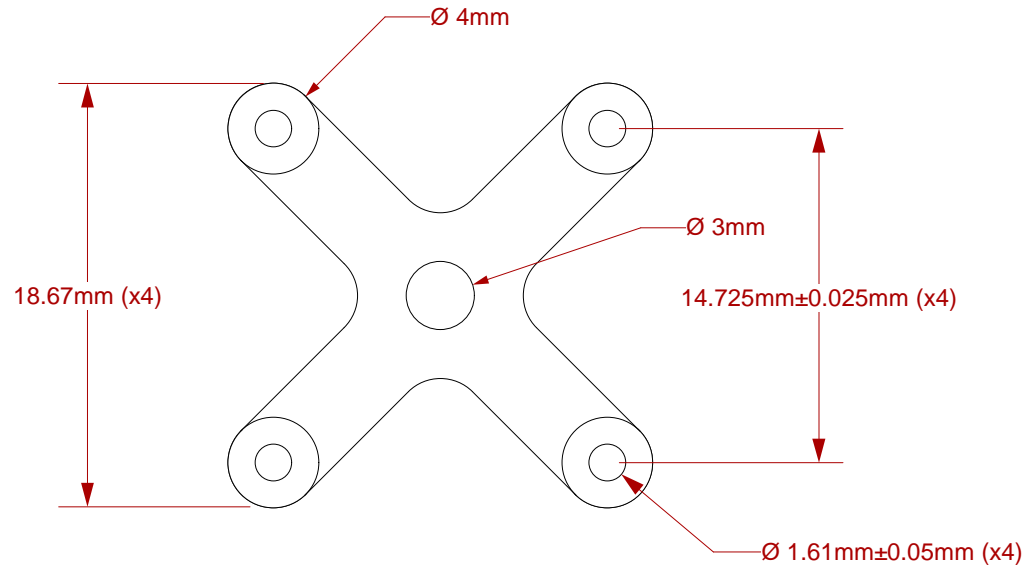
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- ③ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - ④ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - ⑤ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.25
A1	0.16	0.26
b		0.37
D	9.5 BSC	
E	11.5 BSC	
e	0.5 BSC	

18 x 22 array

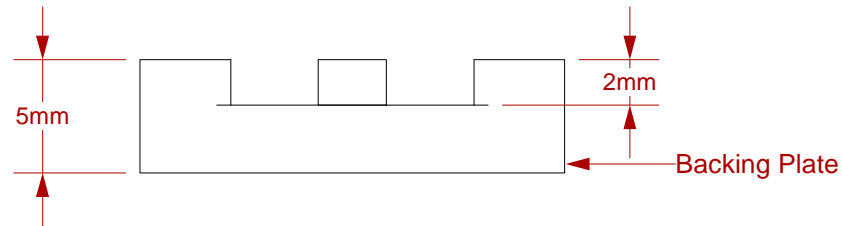
CG-BGA-5005 Drawing		Status: Released	Scale: -	Rev: A
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	File: CG-BGA-5005 Dwg		Modified:	

Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Insulation Plate and Backing Plate

All dimensions are in mm.
All tolerances are $\pm 0.125\text{mm}$.
(Unless stated otherwise)

<p>CG-BGA-5005 Drawing</p>	<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: A</p>
<p>© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>Drawing: Vinayak R</p>		<p>Date: 8/31/09</p>
<p>File: CG-BGA-5005 Dwg</p>		<p>Modified:</p>	